

Title (en)  
EARPHONE, AND ELECTRONIC DEVICE

Title (de)  
KOPFHÖRER UND ELEKTRONISCHE VORRICHTUNG

Title (fr)  
ECOUTEUR ET DISPOSITIF ÉLECTRONIQUE

Publication  
**EP 2456228 A4 20131120 (EN)**

Application  
**EP 09847346 A 20090717**

Priority  
JP 2009062980 W 20090717

Abstract (en)  
[origin: EP2456228A1] An earphone is provided that can be securely mounted in an ear and maintain a good tight fit. An auricle insert part (16) is provided on the outer periphery side face of the speaker housing (14) to accommodate a speaker unit (31) of the earphone. The auricle insert part (16) is continuously formed with the speaker housing (14) and has a protrusion part (33) protruding from the outer periphery side face of the speaker housing (14) to the outside, as part of the auricle insert part (16). The auricle insert part (16) has a side face facing the earlet (114) or the antiragus (115) in the auricle (110) while the speaker housing (14) is arranged between the earlet (114) or the antiragus (115).

IPC 8 full level  
**H04R 1/10** (2006.01)

CPC (source: EP)  
**H04R 1/1091** (2013.01); **H04R 1/1016** (2013.01)

Citation (search report)

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- [XA] US 2009041284 A1 20090212 - TANAKA MASAOKI [JP], et al
- [A] EP 1874080 A2 20080102 - BOSE CORP [US]
- [A] GB 2220819 A 19900117 - SONY CORP [JP]
- [A] EP 2071867 A1 20090617 - HOSIDEN CORP [JP]
- See references of WO 2011007448A1

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